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Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No.	Applicant(s)	
	10/664,387	KIM ET AL.	
	Examiner	Art Unit	
	Albert H. Cutler	2622	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) Responsive to communication(s) filed on 30 April 2007.
- 2a) This action is FINAL. 2b) This action is non-final.
- 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) Claim(s) 1-30 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) Claim(s) _____ is/are allowed.
- 6) Claim(s) 1-30 is/are rejected.
- 7) Claim(s) _____ is/are objected to.
- 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) The specification is objected to by the Examiner.
- 10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) All b) Some * c) None of:
1. Certified copies of the priority documents have been received.
2. Certified copies of the priority documents have been received in Application No. _____.
3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) Notice of References Cited (PTO-892)
- 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) Information Disclosure Statement(s) (PTO/SB/08)
Paper No(s)/Mail Date _____
- 4) Interview Summary (PTO-413)
Paper No(s)/Mail Date _____
- 5) Notice of Informal Patent Application
- 6) Other: _____

DETAILED ACTION

1. This office action is responsive to communication filed on April 30, 2007.

Response to Arguments

2. Applicant's arguments filed April 30, 2007 have been fully considered but they are not persuasive.
3. Applicant states, with regards to the LED and image capture device, "Therefore, an important feature of the present invention is that the subject camera module includes a flash generating LED, an image capture device are formed separately of a motherboard of a mobile communication terminal (as described in par. 58 of the specification). As a result, the LED unit and the image capture device can be separately rotated independently of the movement of said motherboard. Moreover, these units can either formed directly on the flexible PC. or can be attached to a rigid PC board and the connected to each other by an FPC. In either case, because they are separate and distinct from the motherboard of the mobile communication unit, they can be made smaller and therefore require less space. These features are clearly recited in the independent claims."
4. As stated above, Applicant has pointed out that the LED unit and image capture device of the present invention are separate and distinct from the motherboard of the mobile communication unit, and that these features are clearly recited in the independent claims. However, after the inspection of the independent claims, the Examiner has found no mention of a motherboard, or that the LED unit and image capture device are separate and distinct from any motherboard. Therefore, the

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Examiner respectfully disagrees that these limitations are recited in the independent claims.

5. In response to applicant's argument that the references fail to show certain features of applicant's invention, it is noted that the features upon which applicant relies (i.e., the motherboard of the mobile communication unit, and the position of the LED unit and image capture device in relation to said motherboard) are not recited in the rejected claim(s). Although the claims are interpreted in light of the specification, limitations from the specification are not read into the claims. See *In re Van Geuns*, 988 F.2d 1181, 26 USPQ2d 1057 (Fed. Cir. 1993).

6. Applicant argues, with respect to Kuroda, "While, at least one camera unit is mounted on a PC board 13 and is connected by a flexible cable 16 to the motherboard 14, the Applicants could not find anywhere in this reference anything that would indicate that the flash12 is mounted on the motherboard." Applicant then again asserts, "More specifically, as discussed above, the present invention pertains to a camera module that is separate from the motherboard of a mobile telephone and communicates therewith (for example to obtain power, and or to receive trigger signals) via a separate connector."

7. The Examiner respectfully disagrees. In figure 7, Kuroda teaches a flash(12) and a main PC board(14). As there is nothing between the flash(12) and the main PC board(14), as evidenced by figure 7, the flash(12) is clearly **mounted on** the main PC board(14). Furthermore, Kuroda teaches of the main PC board(14), and nowhere teaches that the main PC board(14) is the motherboard of the mobile communication

device, although these features are not expressly limited by the current claimed subject matter of the present invention.

8. Applicant argues, "Kuroda does not teach a mobile phone with a motherboard and a separate camera module."

9. The Examiner respectfully disagrees. The Examiner has found that nowhere in the claimed subject matter is it stated that any so-called motherboard of the mobile phone is separate from the camera module. Furthermore, Kuroda nowhere teaches that the camera module is not separate from the motherboard of the mobile phone.

10. Finally, Applicant argues, "the prior art fails to teach a camera module with a camera unit, a flash unit, a flexible PC interconnecting the two the camera module being separate from the mother board of the mobile phone."

11. The Examiner respectfully disagrees. Kuroda teaches a camera module with a camera unit, a flash unit, a flexible PC interconnecting the two(see claim 1 rationale).

Figure 7 clearly demonstrates that the flexible PC(16) is electrically connected **between** the flash unit(12) and camera unit(6 or 10) as specified by claim 1 of the present invention. Once more, the Examiner has found that nowhere in the claimed subject matter it is stated that any so-called motherboard of the mobile phone is separate from the camera module. Furthermore, Kuroda nowhere teaches that the camera module is not separate from the motherboard of the mobile phone.

12. It should be noted that the common knowledge of the old and well-known statements made by the Examiner with regards to claims 7, 8, 9, and 29 is taken as **admitted prior art** because Applicant failed to seasonably traverse this common

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knowledge from the amendment filed on April 30, 2007. See MPEP § 2144.03. In re Chevenard, 60 USPQ 239 (CCPA 1943).

13. Therefore, the Examiner is maintaining the rejection.

Claim Rejections - 35 USC § 103

14. The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.

15. Claims 1, 3, 4, and 5-9 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kuroda(US Patent Application Publication 2003/0036365) in view of Rinaldi et al.(US Patent Application Publication 2003/0057430).

Consider claim 1, Kuroda teaches:

A camera module("upper casing", 1a, figures 6 and 7, paragraphs 34-44) for mobile communication terminals("mobile phone main unit", 1, paragraph 0033), comprising:

an image capture device unit("camera module", 6, figure 7) for focusing an image of a subject("suitable for close range photography" paragraph 0034); a light emitting unit("flash", 12, figures 6 and 7) for emitting light to the subject("having a strong illumination function so as to allow photography in a dark place" paragraph 0035); a FPC (flexible printed circuit)(“flexible printed circuit board”, 16, paragraph 0036, figure 7) electrically connected between the image capture device unit and the light emitting unit(see figure 7, “the close-range camera module(6) is connected to a connector(15) mounted on a main printed circuit board(14) inside the upper casing(1a)” paragraph

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0036, The flash is mounted on the main printed circuit board(14.); and a connector unit("connector(15)", paragraph 0036, figure 7) for applying an electric signal to the image capture device unit(6, figure 7).

However, Kuroda does not explicitly teach that the light emitting unit is an LED.

Like Kuroda, Rinaldi et al. teaches of imaging(paragraph 0005). Rinaldi et al. also teaches of using printed circuit boards(paragraph 0004). Rinaldi et al. teaches of a method for fabrication of SMD-LED's on a wafer(paragraphs 0023-0025). In figures 5A and 5B, paragraph 0025, Rinaldi et al. teaches of LED's connected to a printed circuit board.

In addition to the teachings of Kuroda, Rinaldi et al. teaches that LED's are extremely versatile and good for displaying images due to the fact that they can be relatively small and don't burn out(Rinaldi et al., paragraph 0005).

Therefore, it would have been obvious to a person having ordinary skill in the art at the time of the invention to use an LED as taught by Rinaldi et al. as the flash device in the camera module taught by Kuroda because LED's are extremely versatile and good for displaying images due to the fact that they can be relatively small and don't burn out(Rinaldi et al., paragraph 0005).

Consider claim 3, and as applied to claim 1 above, Kuroda teaches:

The light emitting unit(12, figures 6 and 7) comprises:

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A light emitting unit PCB("main printed circuit board", 14, figure 7) formed so that the light emitting unit(12) is mounted thereon(see figure 7). Rinaldi et al. teaches that the light emitting unit is an LED(see claim 1 rationale).

Consider claim 4, and as applied to claim 3 above, Kuroda teaches that the light emitting unit(12) is attached to the light emitting unit PCB(14) upside down(see figure 7). Rinaldi et al. teaches that the light emitting unit is an LED(see claim 1 rationale).

Consider claim 5 and as applied to claim 1 above, Kuroda teaches that the light emitting unit(12) is mounted on the housing of the image capture device(6)(“the close-range camera module(6) is connected to a connector(15) mounted on a main printed circuit board(14) inside the upper casing 1a, via a flexible printed circuit board(16)”, paragraph 0036. The light emitting unit(12) is mounted on same PCB(14) that connector(15), connected to the housing of the image capture device(6), is mounted on. Therefore, the light emitting unit(12) is mounted on the housing of image capture device(6.). Rinaldi et al. teaches that the light emitting unit is an LED(see claim 1 rationale).

Consider claim 6, and as applied to claim 1 above, Kuroda further teaches that the light emitting unit(12) further comprises a retainer("flash window", 17, figure 7, paragraph 0038) for guiding the light emitted("the flash(12) is exposed through a flash

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window(17)" paragraph 0038) from the light emitting unit(12). Rinaldi et al. teaches that the light emitting unit is an LED(see claim 1 rationale).

Consider claim 7 and as applied to claim 1 above, Kuroda teaches of an image capture device unit(6) connected to a light emitting unit(12) via a FPC(16). Rinaldi et al. teaches that the light emitting unit is an LED(see claim 1 rationale).

The combined invention of Kuroda and Rinaldi et al. does not explicitly teach that the image capture device unit and the LED are electrically connected to the FPC, respectively, via a flexible cable connector.

However, Official Notice (MPEP § 2144.03) is taken that both the concepts and advantages of using a flexible cable connector to connect circuit boards are well known and expected in the art. It would have been obvious to a person having ordinary skill in the art at the time of the invention to use a flexible cable connector to connect the LED PCB and image capture device unit to the FPC as taught by the combination of Kuroda and Rinaldi et al. for the benefit of providing electrically-efficient connections with the flexibility that contacts that can be easily removed from the wiring side when necessary for maintenance and repair.

Consider claim 8, and as applied to claim 1 above, Kuroda teaches of an image capture device unit(6) connected to a light emitting unit(12) via a FPC(16). Rinaldi et al. teaches that the light emitting unit is an LED(see claim 1 rationale).

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The combined invention of Kuroda and Rinaldi et al. does not explicitly teach that the image capture device unit and the LED are electrically connected to the FPC, respectively, by soldering.

However, Official Notice (MPEP § 2144.03) is taken that both the concepts and advantages of using soldering to connect circuit boards are well known and expected in the art. It would have been obvious to a person having ordinary skill in the art at the time of the invention to use soldering to connect the LED PCB and image capture device unit to the FPC as taught by the combination of Kuroda and Rinaldi et al. for the benefit of being able to use much smaller component connections, allowing much higher circuit densities, achieving a high degree of automation, reducing labor cost and greatly increasing production rates.

Consider claim 9, and as applied to claim 1 above, Kuroda teaches of an image capture device unit(6) connected to a light emitting unit(12) via a FPC(16). Rinaldi et al. teaches that the light emitting unit is an LED(see claim 1 rationale).

The combined invention of Kuroda and Rinaldi et al. does not explicitly teach that the image capture device unit and the LED are electrically connected to the FPC, respectively, by means of anisotropic conductive film, anisotropic conductive paste, or adhesive resin.

However, Official Notice (MPEP § 2144.03) is taken that both the concepts and advantages of using anisotropic conductive film to connect circuit boards are well known and expected in the art. It would have been obvious to a person having ordinary skill in

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the art at the time of the invention to use anisotropic conductive film to connect the LED PCB and image capture device unit to the FPC as taught by the combination of Kuroda and Rinaldi et al. for the benefit of minimizing space requirements, replacing solder with a lead-free solution, and reducing costs by replacing cable connectors.

16. Claims 2, 10-14, 23, 25/23, 26/23, and 27/23 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kuroda(US Patent Application Publication 2003/0036365) in view of Rinaldi et al.(US Patent Application Publication 2003/0057430), and further in view of Yamada et al.(US Patent Application Publication 2001/0050717).

Consider claim 2, and as applied to claim 1 above, the combination of Kuroda and Rinaldi et al. teach of an image capture device unit(see claim 1 rationale). Kuroda teaches that the image capture device unit(6) comprises a housing(see figure 7, paragraph 0036). Kuroda also teaches that the housing has a camera lens("lens", 6a, paragraph 0036) disposed to the upper part of the housing(see figure 7) for focusing the image of the subject; and an image capture device PCB (printed circuit board)("camera module printed circuit board" 13, figure 7) adapted for supporting the housing(see figure 7),

However, Kuroda does not explicitly teach that the housing has a space defined therein, or that the PCB has an image sensor for capturing the image of the subject mounted to the middle upper surface thereof.

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Yamada et al. teaches of a camera device having a similar structure to that taught by Kuroda(see figure 1, paragraph 0039-0044). Like Kuroda, the device of Yamada et al. contains a connector(8) for connecting the imaging device to a motherboard(7). Yamada et al. also teaches of the use of a flexible printed circuit("flexible wiring board", 5, figure 1) for connecting a camera module("CMOS Camera", 20, figure 1). The device of Yamada et al. also contains a lens(2, figures 1 and 2).

In addition to the teachings of Kuroda, Yamada et al. explicitly teaches the internal components of the image capture device unit(20). Yamada et al. teaches of a housing(20, figure 2) having a space defined therein("image pick-up opening", 22, figure 2). Yamada et al. also teaches the PCB("wiring board", 21) has an image sensor("image pickup semiconductor", 4) for capturing the image of the subject mounted to the middle upper surface thereof(The image sensor is mounted on the upper middle surface of the wiring board(21), see figure 2).

Therefore, it would have been obvious to a person having ordinary skill in the art at the time of the invention to use image capture device(20) taught by Yamada et al. as the image capture device(6) taught by the combination of Kuroda and Rinaldi et al. because the device of Yamada et al. provides the benefit of integrating more than one device, which would otherwise be mounted separately, into a single housing and thereby making the overall device even more compact, and more cost and labor efficient due to the fact that only one part, as opposed to multiple parts, would have to be mounted(paragraph 0009).

Consider claim 10, Kuroda teaches:

A camera module("upper casing", 1a, figures 6 and 7, paragraphs 34-44) for mobile communication terminals("mobile phone main unit", 1, paragraph 0033), comprising:

an image capture device unit("camera module", 6, figure 7) for focusing an image of a subject("suitable for close range photography" paragraph 0034);

a light emitting unit("flash", 12, figures 6 and 7) for emitting light to the subject("having a strong illumination function so as to allow photography in a dark place" paragraph 0035);

a FPC("flexible printed circuit board", 16, paragraph 0036, figure 7) including a first part(13) formed so that the image capture device(6) unit is mounted thereon(see figure 7, paragraph 0036), a second part(14) formed so that the light emitting unit(12) is mounted thereon(see figure 7), and a connection part(15) for electrically connecting the first part(13) and the second part(14), the first part(13) and the second part(14) being integrally formed with the connection part(15) (see figure 7, "the close-range camera module(6) is connected to a connector(15) mounted on a main printed circuit board(14) inside the upper casing(1a)" paragraph 0036, The flash is mounted on the main printed circuit board(14).); and

a connector unit("connector(15)", paragraph 0036, figure 7) for applying an electric signal to the FPC(16)(The connector(15) attaches the FPC(16) to the main PCB(14) which supplies electric signals.)

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However, Kuroda does not explicitly teach that the light emitting unit is an LED, or that the image capture device and LED are directly mounted on flexible printed circuits.

Like Kuroda, Rinaldi et al. teaches of imaging(paragraph 0005). Rinaldi et al. also teaches of using printed circuit boards(paragraph 0004). Rinaldi et al. teaches of a method for fabrication of SMD-LED's on a wafer(paragraphs 0023-0025). In figures 5A and 5B, paragraph 0025, Rinaldi et al. teaches of LED's connected to a printed circuit board.

In addition to the teachings of Kuroda, Rinaldi et al. teaches that LED's are extremely versatile and good for displaying images due to the fact that they can be relatively small and don't burn out(Rinaldi et al., paragraph 0005).

Therefore, it would have been obvious to a person having ordinary skill in the art at the time of the invention to use an LED as taught by Rinaldi et al. as the flash device in the camera module taught by Kuroda because LED's are extremely versatile and good for displaying images due to the fact that they can be relatively small and don't burn out(Rinaldi et al., paragraph 0005).

Yamada et al. teaches of a camera device having a similar structure to that taught by Kuroda(see figure 1, paragraph 0039-0044). Like Kuroda, the device of Yamada et al. contains a connector(8) for connecting the imaging device to a motherboard(7). Yamada et al. also teaches of the use of a flexible printed circuit("flexible wiring board", 5, figure 1) for connecting a camera module("CMOS

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Camera", 20, figure 1). The device of Yamada et al. also contains a lens(2, figures 1 and 2). Where Yamada et al. differs is that the use of a flash device is not taught.

In addition to the teachings of Kuroda, Yamada et al. explicitly teaches of mounting components directly on an FPC. In the eleventh embodiment of the disclosed invention, paragraphs 0093-0099, figure 11, Yamada et al. teaches that an image pick-up semiconductor(4) and image processing semiconductor(9) are mounted on a flexible wiring board(5). The reason that one is motivated to mount components directly on the an FPC is that a more compact and less costly device is created(Yamada et al., paragraph 0099).

Therefore, it would have been obvious to a person having ordinary skill in the art at the time of the invention to mount the image capture device and light emitting unit taught by Kuroda directly on the FPC as taught by Yamada et al. because mounting components directly on an FPC provides the benefit of removing the rigid wiring board connected to the FPC and thus producing a device which can be made more compact to a greater extent and made much less costly(paragraph 0099).

Consider claim 11; and as applied to claim 10 above, Kuroda teaches:
the image capture device unit(6) comprises:
a housing(see figure 7, paragraph 0036) supported by the first part(13);
a camera lens(6a) disposed to the upper part of the housing(see figure 7) for focusing the image of the subject;

However, Kuroda does not explicitly teach that the housing has a space defined therein, that the image capture device is mounted directly on the FCB, or that the image capture device has an image sensor mounted directly on the FCB.

Yamada et al. teaches that the housing(20, figure 11) has a space defined therein("image pick-up opening", 22, figure 2, This area is also shown, although not labeled, in figure 11.), that the image capture device(20) is mounted directly on the FCB(see claim 10 rationale), and the image capture device(20) has an image sensor(4) mounted directly on the FCB(see claim 10 rationale, figure 11, paragraph 0094).

Consider claim 12, and as applied to claim 10 above, Kuroda further teaches that the light emitting unit(12) is attached to the light emitting unit PCB(14) upside down(see figure 7).

Consider claim 13, and as applied to claim 10 above, Kuroda further teaches that the light emitting unit(12) is mounted on the housing of the image capture device(6)(“the close-range camera module(6) is connected to a connector(15) mounted on a main printed circuit board(14) inside the upper casing(1a), via a flexible printed circuit board(16)”, paragraph 0036. The light emitting unit(12) is mounted on same PCB(14) that connector(15), connected to the housing of the image capture device(6), is mounted on. Therefore, the light emitting unit(12) is mounted on the housing of image capture device(6).)

Consider claim 14 and as applied to claim 10 above, Kuroda further teaches that the light emitting unit(12) further comprises a retainer("flash window", 17, figure 7, paragraph 0038) for guiding the light emitted("the flash(12) is exposed through a flash window(17)" paragraph 0038) from the light emitting unit(12).

Consider claim 23, Kuroda teaches:

A camera module(6, figures 6 and 7) for mobile communication terminals(1), comprising:

a housing(see figure 7, paragraph 0036);

a camera lens(6a) disposed to the upper part of the housing(6) for focusing an image of a subject;

a PCB(13) adapted for supporting the housing(6);

at least one light emitting unit(12) disposed on the PCB(see figure 7, There is no distinguishable space between PCB(13) and PCB(14). Therefore it is reasonable that the two PCBs are integrated as one large PCB with two parts.) outside the housing(6, see figure 7) for emitting light to the subject("having a strong illumination function so as to allow photography in a dark place" paragraph 0035);

and a connector unit(15) for applying an electric signal to the PCB(13).

However, Kuroda does not explicitly teach that the housing has a space defined therein, or that the PCB has an image sensor for capturing the image of the subject mounted to the middle upper surface thereof, or that the light emitting unit is an LED.

Like Kuroda, Rinaldi et al. teaches of imaging(paragraph 0005). Rinaldi et al. also teaches of using printed circuit boards(paragraph 0004). Rinaldi et al. teaches of a method for fabrication of SMD-LED's on a wafer(paragraphs 0023-0025). In figures 5A and 5B, paragraph 0025, Rinaldi et al. teaches of LED's connected to a printed circuit board.

In addition to the teachings of Kuroda, Rinaldi et al. teaches that LED's are extremely versatile and good for displaying images due to the fact that they can be relatively small and don't burn out(Rinaldi et al., paragraph 0005).

Therefore, it would have been obvious to a person having ordinary skill in the art at the time of the invention to use an LED as taught by Rinaldi et al. as the flash device in the camera module taught by Kuroda because LED's are extremely versatile and good for displaying images due to the fact that they can be relatively small and don't burn out(Rinaldi et al., paragraph 0005),

Yamada et al. teaches of a camera device having a similar structure to that taught by Kuroda(see figure 1, paragraph 0039-0044). Like Kuroda, the device of Yamada et al. contains a connector(8) for connecting the imaging device to a motherboard(7). Yamada et al. also teaches of the use of a flexible printed circuit("flexible wiring board", 5, figure 1) for connecting a camera module("CMOS Camera", 20, figure 1). The device of Yamada et al. also contains a lens(2, figures 1 and 2). Where Yamada et al. differs is that the use of a flash device is not taught.

In addition to the teachings of Kuroda, Yamada et al. explicitly teaches the internal components of the image capture device unit(20). Yamada et al. teaches of a

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housing(20, figure 2) having a space defined therein("image pick-up opening", 22, figure 2). Yamada et al. also teaches the PCB("wiring board", 21) has an image sensor("image pickup semiconductor", 4) for capturing the image of the subject mounted to the middle upper surface thereof(The image sensor is mounted on the upper middle surface of the wiring board(21), see figure 2).

Therefore, it would have been obvious to a person having ordinary skill in the art at the time of the invention to use the image capture device(20) taught by Yamada et al. as the image capture device(6) taught by Kuroda because the device of Yamada et al. provides the benefit of integrating more than one device, which would otherwise be mounted separately, into a single housing and thereby making the overall device even more compact, and more cost and labor efficient due to the fact that only one part, as opposed to multiple parts, would have to be mounted(paragraph 0009).

Consider claim 25 and as applied to claim 23 above Kuroda does not explicitly teach:

an iris filter (IR filter) disposed in the space of the housing for controlling an amount of light of the image focused from the camera lens.

However, Yamada et al. teaches:

an iris filter (IR filter)(24, figure 2; paragraph 0041) disposed in the space of the housing(20, see figure 2) for controlling an amount of light of the image focused from the camera lens(Filter(24) is an "infrared-ray cutting filter", paragraph 0041).

Consider claim 26 and as applied to claim 23 above, Kuroda does not explicitly teach a lens holder, wherein the camera lens(6a) is attached to the housing via a lens holder.

However, Yamada et al. teaches:

a lens holder, wherein the camera lens(2) is attached to the housing(20) via a lens holder(see figure 2, the lens(2) is supported by two supports(i.e. a lens holder) on the sides of the housing(20)).

Consider claim 27 and as applied to claim 23 above Kuroda does not explicitly teach that the LED is an SMD LED.

However, Yamada et al. teaches that the LED is an SMD-LED(see paragraph 0021, figure 5B).

17. Claims 15, 17, 18, and 19 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kuroda(US Patent Application Publication 2003/0036365) in view of Rinaldi et al.(US Patent Application Publication 2003/0057430) and further in view of Cibulsky et al.(US Patent 5,378,306).

Consider claim 15, Kuroda teaches:

A camera module("upper casing", 1a, figures 6 and 7, paragraphs 34-44) for mobile communication terminals("mobile phone main unit", 1, paragraph 0033), comprising:

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an image capture device unit("camera module", 6, figure 7) for focusing an image of a subject("suitable for close range photography" paragraph 0034);

a light emitting unit("flash", 12, figures 6 and 7) for emitting light to the subject("having a strong illumination function so as to allow photography in a dark place" paragraph 0035);

a connection unit including a first rigid part(13) formed so that the image capture device unit(6) is mounted thereon(see figure 7), a second rigid part(14) formed so that the LED(12) is mounted thereon(see figure 7), and a flexible connection part(16) for electrically connecting the first rigid part(13) and the second rigid part(14) (see figure 7, "the close-range camera module(6) is connected to a connector(15) mounted on a main printed circuit board(14) inside the upper casing(1a)" paragraph 0036, The flash is mounted on the main printed circuit board(14).);

and a connector unit("connector(15)", paragraph 0036, figure 7) for applying an electric signal to the circuit board(6, figure 7).

However, Kuroda does not explicitly teach that the light emitting unit(12) is an LED, or that image capture device PCB(13), LED PCB(14), and FPC(16) are integrated as a rigid-flexible PCB.

Like Kuroda, Rinaldi et al. teaches of imaging(paragraph 0005). Rinaldi et al. also teaches of using printed circuit boards(paragraph 0004). Rinaldi et al. teaches of a method for fabrication of SMD-LED's on a wafer(paragraphs 0023-0025). In figures 5A and 5B, paragraph 0025, Rinaldi et al. teaches of LED's connected to a printed circuit board.

In addition to the teachings of Kuroda, Rinaldi et al. teaches that LED's are extremely versatile and good for displaying images due to the fact that they can be relatively small and don't burn out(Rinaldi et al., paragraph 0005).

Therefore, it would have been obvious to a person having ordinary skill in the art at the time of the invention to use an LED as taught by Rinaldi et al. as the flash device in the camera module taught by Kuroda because LED's are extremely versatile and good for displaying images due to the fact that they can be relatively small and don't burn out(Rinaldi et al., paragraph 0005)

Like Kuroda, Cibulski et al. teaches of making circuits for small electronic packages(column 6, lines 46-50). Cibulski et al. teaches that due to the increasing complexity of electronic devices, meeting high performance requirements along with minimum space and weight requirements can be quite a task(column 1, lines 27-33). Therefore, Cibulski et al. teaches a method of producing a rigid-flexible circuit board(column 3, line 46 through column 6, line 27) that overcomes the deficiencies in current circuit boards.

Therefore, it would have been obvious to a person having ordinary skill in the art at the time of the invention to use a rigid-flexible PCB as taught by Cibulski et al. to integrate the image capture device PCB(13), LED PCB(14), and FPC(16) as taught by the combination of Kuroda and Rinaldi et al. because using a rigid-flexible PCB provides the benefit of meeting the performance, space, and weight requirements of increasingly complex electrical circuits(Cibulski et al., column 1, lines 24-36).

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Consider claim 17 and as applied to claim 15 above, Kuroda further teaches that the light emitting unit(12) is attached to the light emitting unit PCB(14) upside down(see figure 7).

Consider claim 18, and as applied to claim 15 above, Kuroda further teaches that the light emitting unit(12) is mounted on the housing of the image capture device unit(6)(“the close-range camera module(6) is connected to a connector(15) mounted on a main printed circuit board(14) inside the upper casing(1a), via a flexible printed circuit board(16)”, paragraph 0036. The light emitting unit(12) is mounted on same PCB(14) that connector(15), connected to the housing of the image capture device(6), is mounted on. Therefore, the light emitting unit(12) is mounted on the housing of image capture device(6).)

Consider claim 19 and as applied to claim 15 above, Kuroda further teaches that the light emitting unit(12) further comprises a retainer(“flash window”, 17, figure 7, paragraph 0038) for guiding the light emitted(“the flash(12) is exposed through a flash window(17)” paragraph 0038) from the light emitting unit(12).

18. Claim 16 is rejected under 35 U.S.C. 103(a) as being unpatentable over Kuroda(US Patent Application Publication 2003/0036365) in view of Rinaldi et al.(US Patent Application Publication 2003/0057430) and in view of Cibulsky et al.(US Patent

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5,378,306) as applied to claim 15 above, and further in view of Yamada et al.(US Patent Application Publication 2001/0050717).

Consider claim 16, and as applied to claim 15 above, Kuroda teaches:

the image capture device unit(6) comprises:

a housing(see figure 7, paragraph 0036) supported by the first rigid part(13);

a camera lens(6a) disposed to the upper part of the housing(see figure 7) for focusing the image of the subject;

However, the combination of Kuroda, Rinaldi et al., and Cibulsky et al. does not explicitly teach that the housing has a space defined therein, that the image capture device is supported by a rigid-flexible PCB, or that the image capture device has an image sensor mounted on the first rigid part(13).

Yamada et al. teaches of a camera device having a similar structure to that taught by Kuroda(see figure 1, paragraph 0039-0044). Like Kuroda, the device of Yamada et al. contains a connector(8) for connecting the imaging device to a motherboard(7). Yamada et al. also teaches of the use of a flexible printed circuit("flexible wiring board", 5, figure 1) for connecting a camera module("CMOS Camera", 20, figure 1). The device of Yamada et al. also contains a lens(2, figures 1 and 2). Where Yamada et al. differs is that the use of a flash device is not taught.

Yamada et al. teaches that the housing(20, figure 11) has a space defined therein("image pick-up opening", 22, figure 2), and that the image capture device(20) has an image sensor(4) mounted on a first rigid part(Yamada et al. teaches the

PCB("wiring board", 21) has an image sensor("image pickup semiconductor", 4) for capturing the image of the subject mounted to the surface thereof(The image sensor is mounted on the surface of the wiring board(21), see figure 2).

Therefore, it would have been obvious to a person having ordinary skill in the art at the time of the invention to use image capture device(20) taught by Yamada et al. as the image capture device(6) taught by the combination of Kuroda, Rinaldi et al., and Cibulski et al. because the device of Yamada et al. provides the benefit of integrating more than one device, which would otherwise be mounted separately, into a single housing and thereby making the overall device even more compact, and more cost and labor efficient due to the fact that only one part, as opposed to multiple parts, would have to be mounted(paragraph 0009).

19. Claims 20 and 21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kuroda(US Patent Application Publication 2003/0036365) in view of Yamada et al.(US Patent Application Publication 2001/0050717).

Consider claim 20, Kuroda teaches:

A camera module(1a) for mobile communication terminals(1), comprising:
an image capture device PCB(13, figure 7);
at least one FPC(16) connected to the image capture device PCB(13);
at least one part-mounting PCB(14) electrically connected to the image capture device PCB(13) via the FPC(16);

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at least one mobile communication terminal part("flash", 12, paragraph 0038) mounted on the part-mounting PCB(14)(see figure 7); and a connector unit(15, paragraph 0036) for applying an electric signal to the image capture device PCB(13).

However, Kuroda does not explicitly teach that the camera module comprises and image sensor for capturing an image of a subject mounted on the upper surface thereof.

Yamada et al. teaches of a camera device having a similar structure to that taught by Kuroda(see figure 1, paragraph 0039-0044). Like Kuroda, the device of Yamada et al. contains a connector(8) for connecting the imaging device to a motherboard(7). Yamada et al. also teaches of the use of a flexible printed circuit("flexible wiring board", 5, figure 1) for connecting a camera module("CMOS Camera", 20, figure 1). The device of Yamada et al. also contains a lens(2, figures 1 and 2). Where Yamada et al. differs is that the use of a flash device is not taught.

In addition to the teachings of Kuroda, Yamada et al. explicitly teaches the internal components of the image capture device unit(20). Yamada et al. teaches of a housing(20, figure 2) having a space defined therein("image pick-up opening", 22, figure 2). Yamada et al. also teaches the PCB("wiring board", 21) has an image sensor("image pickup semiconductor", 4) for capturing the image of the subject mounted to the middle upper surface thereof(The image sensor is mounted on the upper middle surface of the wiring board(21), see figure 2).

Therefore, it would have been obvious to a person having ordinary skill in the art at the time of the invention to use image capture device(20) taught by Yamada et al. as the image capture device(6) taught by Kuroda because the device of Yamada et al. provides the benefit of integrating more than one device, which would otherwise be mounted separately, into a single housing and thereby making the overall device even more compact, and more cost and labor efficient due to the fact that only one part, as opposed to multiple parts, would have to be mounted(paragraph 0009).

Consider claim 21, Kuroda teaches:

A camera module(1a) for mobile communication terminals(1), comprising:
at least one mobile communication terminal part("flash", 12, paragraph 0038);
a connection unit including a first part(13) formed so that the image capture device(6) is mounted thereon(see figure 7), at least one second part(14) formed so that the mobile communication terminal part(12) is mounted thereon(see figure 7), and at least one connection part(16) for electrically connecting the first part(13) and the second part(14)(see paragraph 0036);
and a connector unit(15) for applying an electric signal to the FPC(16).

Yamada et al. teaches of a camera device having a similar structure to that taught by Kuroda(see figure 1, paragraphs 0039-0044). Like Kuroda, the device of Yamada et al. contains a connector(8) for connecting the imaging device to a motherboard(7). Yamada et al. also teaches of the use of a flexible printed circuit("flexible wiring board", 5, figure 1) for connecting a camera module("CMOS

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Camera", 20, figure 1). The device of Yamada et al. also contains a lens(2, figures 1 and 2). Where Yamada et al. differs is that the use of a flash device is not taught.

In addition to the teachings of Kuroda, Yamada et al. explicitly teaches of mounting components directly on an FPC. In the eleventh embodiment of the disclosed invention, paragraphs 0093-0099, figure 11, Yamada et al. teaches that an image pick-up semiconductor(4) and image processing semiconductor(9) are mounted on a flexible wiring board(5). Yamada et al. also teaches that the image capture device(20) has an image sensor(4) for capturing an image of a subject. The reason that one is motivated to mount components directly on the an FPC is that a more compact and less costly device is created(Yamada et al., paragraph 0099).

Therefore, it would have been obvious to a person having ordinary skill in the art at the time of the invention to mount the image capture device and light emitting unit taught by Kuroda directly on the FPC as taught by Yamada et al. because mounting components directly on an FPC provides the benefit of removing the rigid wiring board connected to the FPC and thus producing a device which can be made more compact to a greater extent and made much less costly(paragraph 0099).

20. Claim 22 is rejected under 35 U.S.C. 103(a) as being unpatentable over Kuroda(US Patent Application Publication 2003/0036365) in view of Yamada et al.(US Patent Application Publication 2001/0050717) and further in view of Cibulsky et al.(US Patent 5,378,306).

Consider claim 22, Kuroda teaches:

A camera module(1a, figure 6, figure 7) for mobile communication terminals(1), comprising:

at least one mobile communication terminal part(12);

a connection configuration including a first rigid part(13) formed so that the image capture device(6) is mounted thereon, at least one second rigid part(14) formed so that the mobile communication terminal part(12) is mounted thereon, and at least one flexible connection part(16) for electrically connecting the first rigid part(13) and the second rigid part(14);

and a connector unit(15) for applying an electric signal to the connection unit(paragraph 0036).

However, Kuroda does not explicitly teach that the image capture device(6) contains an image sensor, or that the or that first rigid part(13), second rigid part(14), and FPC(16) are integrated as a rigid-flexible PCB.

Yamada et al. teaches of a camera device having a similar structure to that taught by Kuroda(see figure 1, paragraph 0039-0044). Like Kuroda, the device of Yamada et al. contains a connector(8) for connecting the imaging device to a motherboard(7). Yamada et al. also teaches of the use of a flexible printed circuit("flexible wiring board", 5, figure 1) for connecting a camera module("CMOS Camera", 20, figure 1). The device of Yamada et al. also contains a lens(2, figures 1 and 2). Where Yamada et al. differs is that the use of a flash device is not taught.

In addition to the teachings of Kuroda, Yamada et al. explicitly teaches the internal components of the image capture device unit(20). Yamada et al. teaches of a housing(20, figure 2) having a space defined therein("image pick-up opening", 22, figure 2). Yamada et al. also teaches the PCB("wiring board", 21) has an image sensor("image pickup semiconductor", 4) for capturing the image of the subject mounted to the middle upper surface thereof(The image sensor is mounted on the upper middle surface of the wiring board(21), see figure 2).

Therefore, it would have been obvious to a person having ordinary skill in the art at the time of the invention to use image capture device(20) taught by Yamada et al. as the image capture device(6) taught by Kuroda because the device of Yamada et al. provides the benefit of integrating more than one device, which would otherwise be mounted separately, into a single housing and thereby making the overall device even more compact, and more cost and labor efficient due to the fact that only one part, as opposed to multiple parts, would have to be mounted(paragraph 0009).

Like Kuroda, Cibulski et al. teaches of making circuits for small electronic packages(column 6, lines 46-50). Cibulski et al. teaches that due to the increasing complexity of electronic devices, meeting high performance requirements along with minimum space and weight requirements can be quite a task(column 1, lines 27-33). Therefore, Cibulski et al. teaches a method of producing a rigid-flexible circuit board(column 3, line 46 through column 6, line 27) that overcomes the deficiencies in current circuit boards.

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Therefore, it would have been obvious to a person having ordinary skill in the art at the time of the invention to use a rigid-flexible PCB as taught by Cibulski et al. to integrate the image capture device PCB(13), LED PCB(14), and FPC(16) taught by the combination of Kuroda and Yamada et al., because a rigid-flexible PCB provides the benefit of meeting the performance, space, and weight requirements of increasingly complex electrical circuits(Cibulsky et al. column 1, lines 24-36).

21. Claims 24, 25/24, 26/24, 27/24, 28, 29, and 30 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kuroda(US Patent Application Publication 2003/0036365) in view of Rinaldi et al.(US Patent Application Publication 2003/0057430) and further in view of Yamada et al.(US Patent Application Publication 2001/0050717) as applied to claim 23 above, and further in view of Braithwaite(US Patent 6,540,392).

Consider claim 24 and as applied to claim 23 above, the combined invention of Kuroda, Rinaldi et al., and Yamada et al. does not explicitly teach that the camera module further comprises an optical fiber provided around the LED for forwardly guiding light emitted from the LED.

Like Kuroda, Braithwaite teaches of an imaging system working in correlation with an illumination device(column 1, lines 11-16). Braithwaite addresses the problem of using the illuminator to focusing light efficiently(column 1, line 66 through column 2, line 6).

In addition to the teachings of Kuroda, Braithwaite teaches of an optical fiber(48) provided around an LED(34) for forwardly guiding light emitted from the LED(34)(see column 4, lines 43-64). Braithwaite teaches of using the optical carrier(48) so that light can be routed to the outside of a video camera(column 4, lines 61-64).

Therefore it would have been obvious to a person having ordinary skill in the art at the time of invention to use an optical fiber(48) as taught by Braithwaite around the LED taught by the combined invention of Kuroda, Rinaldi et al., and Yamada et al. for the benefit of being able to remotely place the LED within the housing of the camera unit and still efficiently use the light produced by the LED for illumination outside of the camera(Braithwaite, column 4, lines 61-64).

Consider claim 25 and as applied to claim 24 above Kuroda does not explicitly teach:

an iris filter (IR filter) disposed in the space of the housing for controlling an amount of light of the image focused from the camera lens.

However, Yamada et al. teaches:

an iris filter (IR filter)(24, figure 2, paragraph 0041) disposed in the space of the housing(20, see figure 2) for controlling an amount of light of the image focused from the camera lens(Filter(24) is an "infrared-ray cutting filter", paragraph 0041).

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Consider claim 26 and as applied to claim 24 above, Kuroda does not explicitly teach a lens holder, wherein the camera lens(6a) is attached to the housing via a lens holder.

However, Yamada et al. teaches:

a lens holder, wherein the camera lens(2) is attached to the housing(20) via a lens holder(see figure 2, the lens(2) is supported by two supports(i.e. a lens holder) on the sides of the housing(20)).

Consider claim 27 and as applied to claim 24 above Kuroda does not explicitly teach that the LED is an SMD LED.

However, Yamada et al. teaches that the LED is an SMD-LED(see paragraph 0021, figure 5B).

Consider claim 28, and as applied to claim 24 above, the combined invention of Kuroda, Rinaldi et al., and Yamada et al. does not explicitly teach:

the optical fiber is formed in the shape of a cylinder(see figure 7) comprising a core part and a cladding part surrounding the core part, and
wherein the optical fiber has an open end and a closed end, whereby the optical fiber is fitted around the LED through the open end.

However, Braithwaite teaches:

the optical fiber(48) is formed in the shape of a cylinder(see figure 7) comprising a core part(48) and a cladding part("jacket", 46) surrounding the core part(see figure 7), and

wherein the optical fiber(48) has an open end(bottom end, figure 7) and a closed end(top end, figure 7), whereby the optical fiber(48) is fitted around the LED(34) through the open end(bottom end, A barrel(40) with a bore(42) drilled through is used to encapsulate the optical fiber(48), as well as fit over the top of the LED(34), see figure 7, column 4, lines 43-64.)

Consider claim 29, and as applied to claim 28 above, the combined invention of Kuroda, Rinaldi et al., and Yamada et al. does not explicitly teach that the optical fiber is coated with a flexible conduit tube for preventing any bending or damage to the optical fiber due to external impact.

However, Braithwaite teaches that the optical fiber(48) is coated with a flexible conduit tube("jacket", 46) for preventing any bending or damage to the optical fiber due to external impact(The jacket(46) would protect the optical fiber(48) as is well known in the art.).

Consider claim 30, and as applied to claim 28 above, the combined invention of Kuroda, Rinaldi et al., Yamada et al., and Braithwaite does not explicitly teach that the closed end of the optical fiber(48) is concave.

However, Official Notice (MPEP § 2144.03) is taken that both the concepts and advantages of using an optical fiber(48) with a concave closed end are well known and expected in the art. It would have been obvious to a person having ordinary skill in the art at the time of the invention to use an optical fiber with a concave closed end as the optical fiber(48) taught by the combined invention of Kuroda, Rinaldi et al., Yamada et al., and Braithwaite for the benefit of spreading out those light rays that have been refracted through it, and thus yielding a large coupling angle with a long working distance range compared to a flat-end, or convex-end fiber.

Conclusion

22. The objection made to the specification by the Examiner is hereby removed in view of applicant's response.
23. **THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Albert H. Cutler whose telephone number is (571)-270-1460. The examiner can normally be reached on Mon-Fri (7:30-5:00).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Ngoc-Yen Vu can be reached on (571)-272-7320. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

AC



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